

LED - Lighting and connection technology

Additional information for SMD Terminal blocks 46.121



Strip details

Wiring method	Push In
Cross section (solid)	0.2 - 0.75 mm ²
Cross section (AWG)	24-18
Strip length	8.0 ± 1mm
Conductor entry angle to the PCB	0 - 12°

Material details

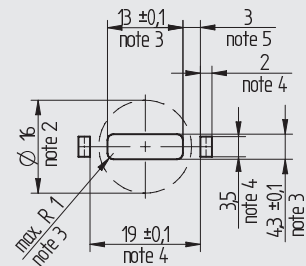
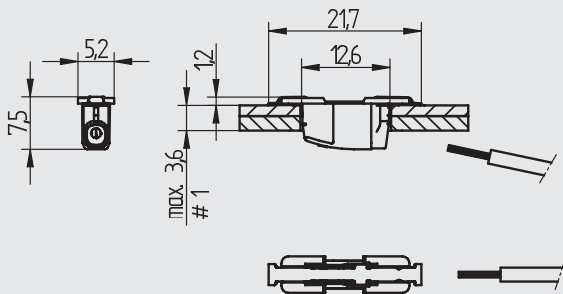
Temperature stability	-40°C bis + 125°C
Lower temperature limit	-40°C
Upper temperature limit	+150°C
Flammability category, based on UL 94	V0
Insulating material group	I
Insulating material	PPA-GF

Important processing notes

Soldering temperature higher 220°C < 60s
 Soldering temperature max. 260°C < 10s

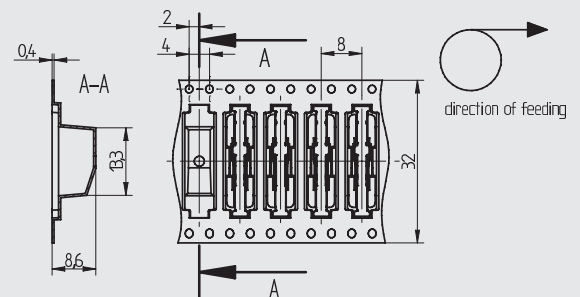
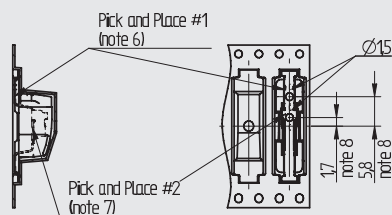
Depending on the SMD soldering process and associated parameters a minor discoloration might occur. However, this will not influence the functionality.

46.121.1002.50



Note 1: Maximum thickness of PCB and heatsink shall not exceed 3.6 mm

- Note 2: Recommendation for opening in heatsink is shown minimum diameter. For smaller diameters or other shaped pockets in heatsink the minimum creepage and clearance distance and manufacturing tolerances have to be considered
- Note 3: Recommended dimension for opening in PCB
- Note 4: Recommended dimension for solder pad
Recommended thickness of solder 0.15 mm
- Note 5: The minimum creepage distance has to be guaranteed, depends on the application.



Notes to the Pick and Place Area:

- Note 6: Recommended Pick and Place area #1
- Note 7: Recommended Pick and Place area #2. Max. diameter of nozzle is 2.5 mm
- Note 8: Distance from center of mass to pick and place area #1 and #2

General note: It is recommended to make an electrical connection between both poles of each polarity on the solder pad.